

Title (en)
SOFT MAGNETIC THERMOSETTING ADHESIVE FILM, SOFT MAGNETIC FILM-LAMINATED CIRCUIT BOARD, AND POSITION-DETECTING DEVICE

Title (de)
WEICHMAGNETISCHE WÄRMEHÄRTENDE HAFTFOLIE, WEICHMAGNETISCHE FOLIENLAMINIERTER LEITERPLATTE UND POSITIONSERKENNUNGSVORRICHTUNG

Title (fr)
FILM MAGNÉTIQUE DOUX ADHÉSIF THERMODURCISSABLE, CIRCUIT IMPRIMÉ STRATIFIÉ SUR UN FILM MAGNÉTIQUE DOUX ET DÉTECTEUR DE POSITION

Publication
EP 2963094 B1 20210623 (EN)

Application
EP 14757328 A 20140120

Priority
• JP 2013035700 A 20130226
• JP 2014050999 W 20140120

Abstract (en)
[origin: EP2963094A1] A soft magnetic thermosetting adhesive film is formed from a soft magnetic thermosetting composition containing soft magnetic particles, acrylic resin, epoxy resin, phenol resin, and a thermosetting catalyst. A total of the epoxy resin content and the phenol resin content is 20 parts by mass or more and 99 parts by mass or less relative to 100 parts by mass of a soft magnetic particles-excluding component excluding the soft magnetic particles from the soft magnetic thermosetting composition.

IPC 8 full level
H01F 1/26 (2006.01); **B32B 7/12** (2006.01); **B32B 27/08** (2006.01); **B32B 27/20** (2006.01); **B32B 27/30** (2006.01); **B32B 27/38** (2006.01); **B32B 27/42** (2006.01); **C08K 3/34** (2006.01); **C08L 33/06** (2006.01); **C08L 63/00** (2006.01); **C09J 7/35** (2018.01); **C09J 11/04** (2006.01); **C09J 133/00** (2006.01); **C09J 161/06** (2006.01); **C09J 161/34** (2006.01); **C09J 163/00** (2006.01); **G06F 3/046** (2006.01); **H01F 41/16** (2006.01)

CPC (source: EP)
B32B 7/12 (2013.01); **B32B 27/08** (2013.01); **B32B 27/20** (2013.01); **B32B 27/308** (2013.01); **B32B 27/38** (2013.01); **B32B 27/42** (2013.01); **C08K 3/34** (2013.01); **C08L 33/06** (2013.01); **C08L 63/00** (2013.01); **C09J 7/35** (2017.12); **C09J 11/04** (2013.01); **C09J 161/06** (2013.01); **C09J 161/34** (2013.01); **G06F 3/046** (2013.01); **H01F 1/26** (2013.01); **B32B 2307/208** (2013.01); **B32B 2307/306** (2013.01); **B32B 2457/08** (2013.01); **H01F 41/16** (2013.01)

Citation (examination)
• US 2010001226 A1 20100107 - ARAMAKI KEISUKE [JP], et al
• US 2010047968 A1 20100225 - AMANO YASUHIRO [JP], et al

Cited by
RU2754260C1; CN110050315A; EP3553801A4; EP3553800A4; RU2754259C1; US2021252840A1; JP2021126873A; CN116631720A; US11783983B2; US11281346B2; US11948720B2; US11387040B2; EP3771974A1

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DOCDB simple family (application)
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